

SNx4AHC86 四路双输入异或门

1 特性

- 工作电压为 2V 至 5.5V V_{CC}
- 闩锁性能超过 250mA，符合 JESD 17 规范
- ESD 保护性能超过 JESD 22 规范要求
 - 2000V 人体放电模型 (A114-A)
 - 200V 机器放电模型 (A115-A)
 - 1000V 充电器件模型 (C101)

2 应用

- 检测输入信号中的相位差
- 创建可选的逆变器或缓冲器

3 描述

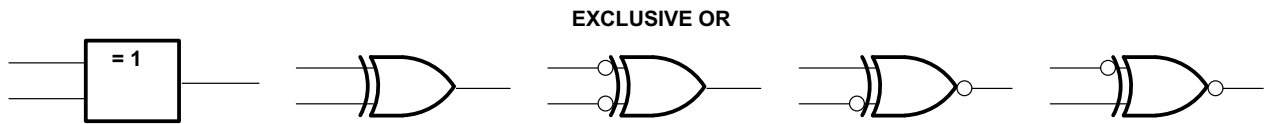
SNx4AHC86 器件是四路双输入异或门。此类器件以正逻辑执行布尔函数 $Y = A \oplus B$ 或 $Y = \bar{A}B + A\bar{B}$ 。

常用作真/补元件。如果一个输入为低电平，则可在输出时重新生成真实形态的其他输入。如果一个输入为高电平，另一个输入的信号则可在输出时重新生成反向信号。

器件信息

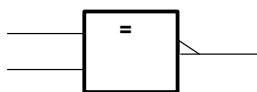
器件型号	额定值	封装 ⁽¹⁾
SN74AHC86	商用级	BQA (WQFN , 14)
		D (SOIC , 14)
		DB (SSOP , 14)
		DGV (TVSOP , 14)
		N (PDIP , 14)
		NS (SOP , 14)
		PW (TSSOP , 14)
SN54AHC86	军用	RGY (VQFN , 14)
		J (CDIP , 14)
		W (CFP , 14)
		FK (LCCC , 20)

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



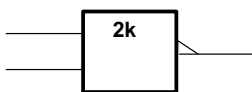
These are five equivalent exclusive-OR symbols valid for an SN74AHC86 gate in positive logic; negation may be shown at any two ports.

LOGIC-IDENTITY ELEMENT



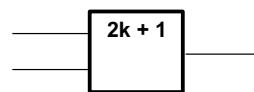
The output is active (low) if all inputs stand at the same logic level (i.e., $A = B$).

EVEN-PARITY ELEMENT



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

ODD-PARITY ELEMENT



The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

异或逻辑



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4 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision K (July 2023) to Revision L (October 2023) Page

- Updated R θ JA values: D = 86 to 124.5, PW = 113 to 147.7, all values in °C/W..... 5
- Added *Application and Implementation* section..... 9

Changes from Revision J (May 2013) to Revision K (July 2023) Page

- 更改了整个文档中的表格、图和交叉参考的编号格式..... 1
- 添加了 *器件信息表*..... 1
- Added the *Device and Documentation Support* sections..... 13
- Added the *Mechanical, Packaging, and Orderable Information* sections..... 13

5 Pin Configuration and Functions

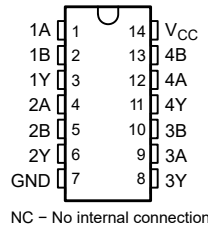


图 5-1. SN54AHC86 J or W Package, SN74AHC86 D, DB, DGV, N, NS, or PW Package, 14-Pin (Top View)

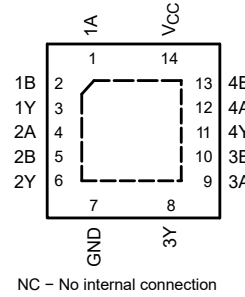


图 5-2. SN74AHC86 RGY Package, VQFN 14-Pin (Top View)

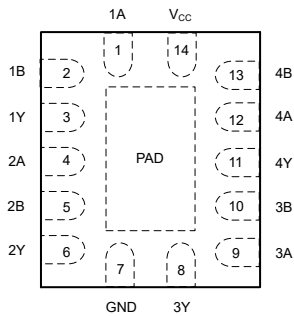


图 5-3. SN74AHC86 BQA Package, WQFN 14-Pin (Top View)

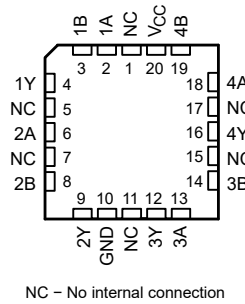


图 5-4. SN54AHC86 FK Package, LCCC 20-Pin (Top View)

表 5-1. Pin Functions

NAME	PIN		TYPE ⁽¹⁾	DESCRIPTION
	D, DB, DGV, N, NS, PW, RGY, J, W, or BQA	FK		
1A	1	2	I	Channel 1, Input A
1B	2	3	I	Channel 1, Input B
1Y	3	4	O	Channel 1, Output Y
2A	4	6	I	Channel 2, Input A
2B	5	8	I	Channel 2, Input B
2Y	6	9	O	Channel 2, Output Y
GND	7	10	G	Ground
3Y	8	12	O	Channel 3, Output Y
3A	9	13	I	Channel 3, Input A
3B	10	14	I	Channel 3, Input B
4Y	11	16	O	Channel 4, Output Y
4A	12	18	I	Channel 4, Input A
4B	13	19	I	Channel 4, Input B
V _{CC}	14	20	P	Positive Supply
NC	—	1, 5, 7, 11, 15, 17	—	Not internally connected
Thermal pad ⁽²⁾			—	The thermal pad can be connected to GND or left floating. Do not connect to any other signal or supply.

(1) Signal Types: I = Input, O = Output, I/O = Input or Output, G = ground, P = power.

(2) BQA package only

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

	VALUE	UNIT
Supply voltage range, V_{CC}	-0.5 to 7	V
Input voltage range, V_I ⁽²⁾	-0.5 to 7	V
Output voltage range, V_O ⁽²⁾	-0.5 to $V_{CC} + 0.5$	V
Input clamp current, I_{IK} ($V_I < 0$)	-20	mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	± 20	mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 25	mA
Continuous current through V_{CC} or GND	± 50	mA
Storage temperature range, T_{stg}	-65 to 150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

6.2 Recommended Operating Conditions

		SN54AHC86		SN74AHC86		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	2	5.5	2	5.5	V
V_{IH}	High-level input voltage	$V_{CC} = 2\text{ V}$		1.5		V
		$V_{CC} = 3\text{ V}$		2.1		
		$V_{CC} = 5.5\text{ V}$		3.85		
V_{IL}	Low-level Input voltage	$V_{CC} = 2\text{ V}$		0.5		V
		$V_{CC} = 3\text{ V}$		0.9		
		$V_{CC} = 5.5\text{ V}$		1.65		
V_I	Input voltage	0	5.5	0	5.5	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 2\text{ V}$		-50		mA
		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		-4		
		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		-8		
I_{OL}	Low-level output current	$V_{CC} = 2\text{ V}$		50		mA
		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		4		
		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		8		
$\Delta t/\Delta v$	Input Transition rise or fall rate	$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		100		ns/V
		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		20		
T_A	Operating free-air temperature	-55	125	-40	125	°C

6.3 Thermal Information

THERMAL METRIC ⁽¹⁾		D ⁽²⁾	DB ⁽²⁾	DGV ⁽²⁾	N ⁽²⁾	NS ⁽²⁾	PW ⁽²⁾	RGY ⁽³⁾	BQA	UNIT
		SOIC	SSOP	TVSOP	PDIP	SOP	TSSOP	VQFN	WQFN	
		14	14	14	14	14	14	14	14	
R _{θJA}	Junction-to-ambient thermal resistance	124.5	96	127	80	76	147.7	47	88.3	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application report.
- (2) The package thermal impedance is calculated in accordance with JESD 51-7.
- (3) The package thermal impedance is calculated in accordance with JESD 51-5

6.4 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		T _A = -40°C TO 125°C		UNIT
						SN54AHC86		SN74AHC86		SN74AHC86		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 μA	2 V	1.9	2	1.9		1.9		1.9		V	
		3 V	2.9	3	2.9		2.9		2.9			
		4.5 V	4.4	4.5	4.4		4.4		4.4			
	I _{OH} = -4 mA	3 V	2.58		2.48		2.48		2.48			
		4.5 V	3.94		3.8		3.8		3.8			
V _{OL}	I _{OL} = 50 μA	2 V		0.1		0.1		0.1		0.1	V	
		3 V		0.1		0.1		0.1		0.1		
		4.5 V		0.1		0.1		0.1		0.1		
	I _{OH} = 4 mA	3 V		0.36		0.5		0.44		0.5		
		4.5 V		0.36		0.5		0.44		0.5		
I _I	V _I = 5.5 V or GND	0 V to 5.5 V		±0.1		±1 ⁽¹⁾		±1		±1	μA	
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V		2		20		20		20	μA	
C _i	V _I = V _{CC} or GND	5 V		4	10				10		pF	

- (1) On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

6.5 Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see [图 7-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C		T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		T _A = -40°C TO 125°C		UNIT
						SN54AHC86		SN74AHC86		SN74AHC86		
				TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	Y	C _L = 15 pF	7 ⁽¹⁾	11 ⁽¹⁾	1 ⁽¹⁾	13 ⁽¹⁾	1	13	1	13	ns
t _{PHL}				7 ⁽¹⁾	11 ⁽¹⁾	1 ⁽¹⁾	13 ⁽¹⁾	1	13	1	13	
t _{PLH}	A or B	Y	C _L = 50 pF	9.5	14.5	1	16.5	1	16.5	1	16.5	ns
t _{PHL}				9.5	14.5	1	16.5	1	16.5	1	16.5	

- (1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

6.6 Switching Characteristics

over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see [图 7-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$		$T_A = -55^\circ\text{C TO } 125^\circ\text{C}$		$T_A = -40^\circ\text{C TO } 85^\circ\text{C}$		$T_A = -40^\circ\text{C TO } 125^\circ\text{C}$		UNIT
				TYP	MAX	SN54AHC86		SN74AHC86		Recommended		
						MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	$C_L = 15\text{ pF}$	4.8 ⁽¹⁾	6.8 ⁽¹⁾	1 ⁽¹⁾	8 ⁽¹⁾	1	8	1	8	ns
t_{PHL}				4.8 ⁽¹⁾	6.8 ⁽¹⁾	1 ⁽¹⁾	8 ⁽¹⁾	1	8	1	8	
t_{PLH}	A or B	Y	$C_L = 50\text{ pF}$	6.3	8.8	1	10	1	10	1	10	ns
t_{PHL}				6.3	8.8	1	10	1	10	1	10	

6.7 Noise Characteristics

$V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ ⁽¹⁾

PARAMETER		SN74AHC86			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.3	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}	-0.3		-0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		4.4		V
$V_{IH(D)}$	High-level dynamic input voltage		3.5		V
$V_{IL(D)}$	Low-level dynamic input voltage			1.5	V

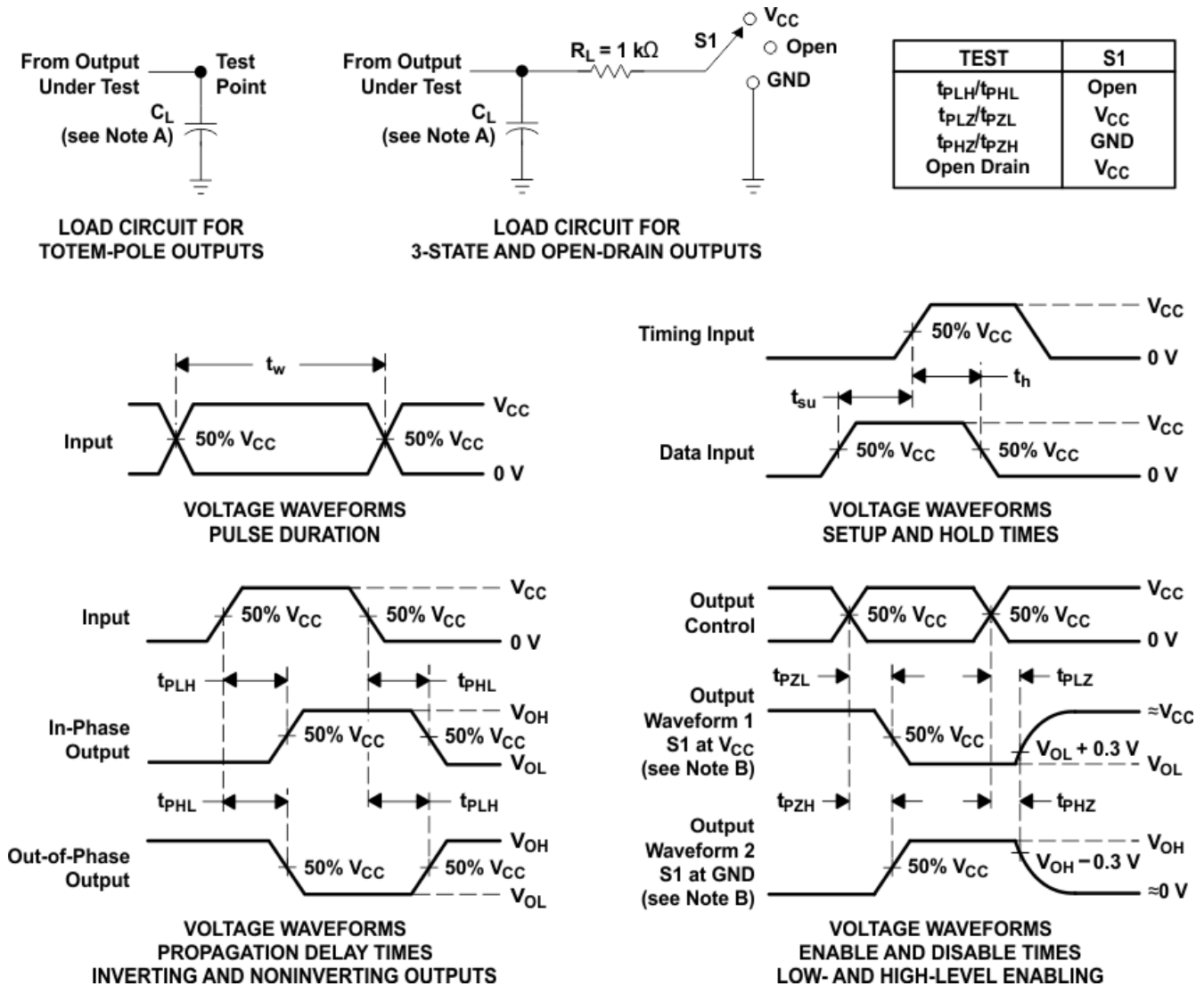
(1) Characteristics are for surface-mount packages only.

6.8 Operating Characteristics

$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	No load, $f = 1\text{ MHz}$	18	pF

7 Parameter Measurement Information



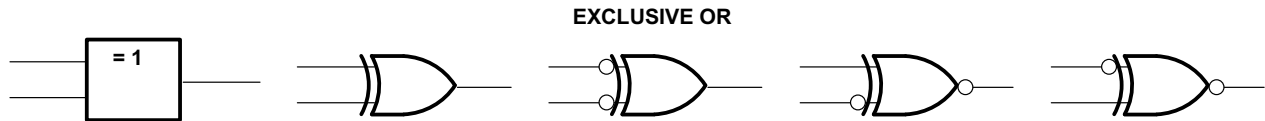
- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

图 7-1. Load Circuit and Voltage Waveforms

8 Detailed Description

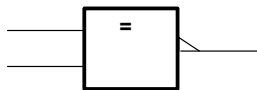
8.1 Functional Block Diagram

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



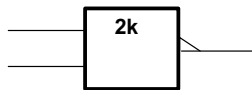
These are five equivalent exclusive-OR symbols valid for an SN74AHC86 gate in positive logic; negation may be shown at any two ports.

LOGIC-IDENTITY ELEMENT



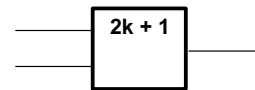
The output is active (low) if all inputs stand at the same logic level (i.e., $A = B$).

EVEN-PARITY ELEMENT



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

ODD-PARITY ELEMENT



The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

图 8-1. Exclusive-OR Logic

8.2 Device Functional Modes

**表 8-1. Function Table
(Each Gate)**

INPUTS		OUTPUT
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	L

9 Application and Implementation

备注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

9.1 Application Information

In this application, three 2-input AND gates are combined to produce a 4-input AND gate function as shown in [图 9-1](#). The fourth gate can be used for another application in the system, or the inputs can be grounded and the channel left unused.

The SN74LV4T08-Q1 is used to directly control the $\overline{\text{RESET}}$ pin of a motor controller. The controller requires four input signals to all be HIGH before being enabled, and should be disabled in the event that any one signal goes LOW. The 4-input AND gate function combines the four individual reset signals into a single active-low reset signal.

9.2 Typical Application

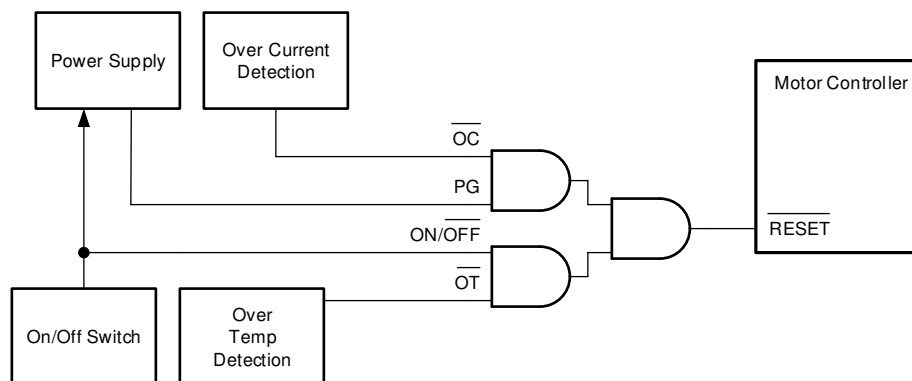


图 9-1. Typical Application Block Diagram

9.2.1 Power Considerations

Ensure the desired supply voltage is within the range specified in the *Recommended Operating Conditions*. The supply voltage sets the electrical characteristics of the device as described in the *Electrical Characteristics* section.

The positive voltage supply must be capable of sourcing current equal to the maximum static supply current, I_{CC} , listed in the *Electrical Characteristics*, and any transient current required for switching.

The ground must be capable of sinking current equal to the total current to be sunk by all outputs of the SNx4AHC86 plus the maximum supply current, I_{CC} , listed in the *Electrical Characteristics*, and any transient current required for switching. The logic device can only sink as much current that can be sunk into its ground connection. Be sure to not exceed the maximum total current through GND listed in the *Absolute Maximum Ratings*.

The SNx4AHC86 can drive a load with a total capacitance less than or equal to 50 pF while still meeting all of the data sheet specifications. Larger capacitive loads can be applied; however, it is not recommended to exceed 50 pF.

The SNx4AHC86 can drive a load with total resistance described by $R_L \geq V_O / I_O$, with the output voltage and current defined in the *Electrical Characteristics* table with V_{OL} . When outputting in the HIGH state, the output

voltage in the equation is defined as the difference between the measured output voltage and the supply voltage at the V_{CC} pin.

Total power consumption can be calculated using the information provided in the [CMOS Power Consumption and Cpd Calculation](#) application note.

Thermal increase can be calculated using the information provided in the [Thermal Characteristics of Standard Linear and Logic \(SLL\) Packages and Devices](#) application note.

小心

The maximum junction temperature, $T_{J(max)}$ listed in the *Absolute Maximum Ratings*, is an additional limitation to prevent damage to the device. Do not violate any values listed in the *Absolute Maximum Ratings*. These limits are provided to prevent damage to the device.

9.2.1.1 Input Considerations

Input signals must cross to be considered a logic LOW, and to be considered a logic HIGH. Do not exceed the maximum input voltage range found in the *Absolute Maximum Ratings*.

Unused inputs must be terminated to either V_{CC} or ground. The unused inputs can be directly terminated if the input is completely unused, or they can be connected with a pull-up or pull-down resistor if the input will be used sometimes, but not always. A pull-up resistor is used for a default state of HIGH, and a pull-down resistor is used for a default state of LOW. The drive current of the controller, leakage current into the SNx4AHC86 (as specified in the *Electrical Characteristics*), and the desired input transition rate limits the resistor size. A 10-k Ω resistor value is often used due to these factors.

Refer to the *Feature Description* section for additional information regarding the inputs for this device.

9.2.1.2 Output Considerations

The ground voltage is used to produce the output LOW voltage. Sinking current into the output will increase the output voltage as specified by the V_{OL} specification in the *Electrical Characteristics*.

Unused outputs can be left floating. Do not connect outputs directly to V_{CC} or ground.

Refer to the *Feature Description* section for additional information regarding the outputs for this device.

9.2.2 Detailed Design Procedure

1. Add a decoupling capacitor from V_{CC} to GND. The capacitor needs to be placed physically close to the device and electrically close to both the V_{CC} and GND pins. An example layout is shown in the *Layout* section.
2. Ensure the capacitive load at the output is ≤ 50 pF. This is not a hard limit; it will, however, ensure optimal performance. This can be accomplished by providing short, appropriately sized traces from the SN74AHC1G04-Q1 to one or more of the receiving devices.
3. Ensure the resistive load at the output is larger than $(V_{CC} / I_{O(max)}) \Omega$, so that the maximum output current from the *Absolute Maximum Ratings* is not violated. Most CMOS inputs have a resistive load measured in $M\Omega$; much larger than the minimum calculated previously.
4. Thermal issues are rarely a concern for logic gates; the power consumption and thermal increase, however, can be calculated using the steps provided in the application report, [CMOS Power Consumption and Cpd Calculation](#).

9.2.3 Application Curves

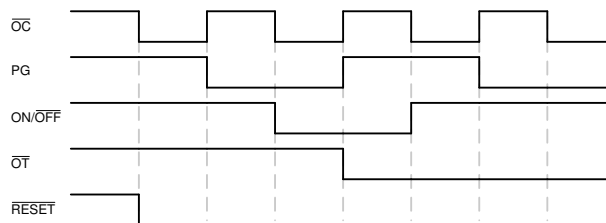


图 9-2. Application Timing Diagram

9.3 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- μ F capacitor is recommended for this device. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise. The 0.1- μ F and 1- μ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results, as shown in the following layout example.

9.4 Layout

9.4.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices, inputs must never be left floating. In many cases, functions or parts of functions of digital logic devices are unused (for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used). Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC} , whichever makes more sense for the logic function or is more convenient.

9.4.1.1 Layout Example

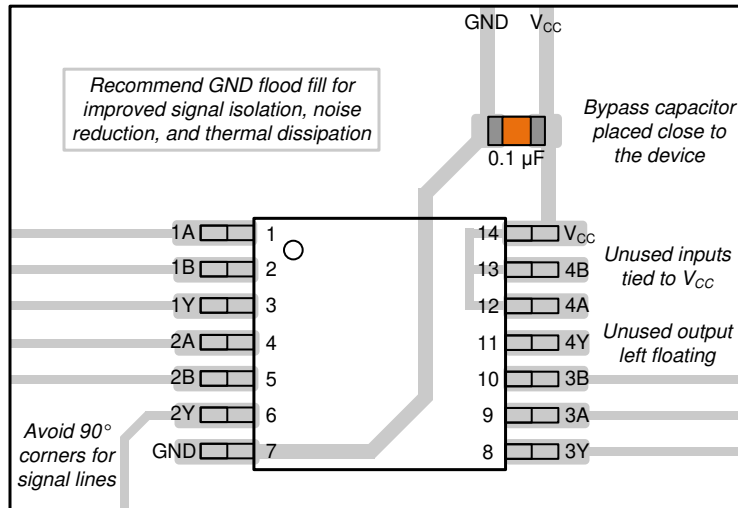


图 9-3. Example Layout for the SNx4AHC86

10 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

10.1 Documentation Support (Analog)

10.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [CMOS Power Consumption and Cpd Calculation application note](#)
- Texas Instruments, [Designing With Logic application note](#)
- Texas Instruments, [Thermal Characteristics of Standard Linear and Logic \(SLL\) Packages and Devices application note](#)
- Texas Instruments, [Implications of Slow or Floating CMOS Inputs application note](#)

10.2 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](#) 上的器件产品文件夹。点击 [通知](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

10.3 支持资源

TI E2E™ [中文支持论坛](#) 是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [使用条款](#)。

10.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
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10.5 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

10.6 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9681601Q2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9681601Q2A SNJ54AHC86FK	Samples
5962-9681601QCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9681601QCA SNJ54AHC86J	Samples
5962-9681601QDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9681601QDA SNJ54AHC86W	Samples
SN74AHC86BQAR	ACTIVE	WQFN	BQA	14	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC86	Samples
SN74AHC86D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-40 to 125	AHC86	
SN74AHC86DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA86	Samples
SN74AHC86DGVR	ACTIVE	TVSOP	DGV	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA86	Samples
SN74AHC86DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC86	Samples
SN74AHC86N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 125	SN74AHC86N	Samples
SN74AHC86NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC86	Samples
SN74AHC86PW	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 125	HA86	
SN74AHC86PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	HA86	Samples
SN74AHC86RGYR	ACTIVE	VQFN	RGY	14	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HA86	Samples
SNJ54AHC86FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9681601Q2A SNJ54AHC86FK	Samples
SNJ54AHC86J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9681601QCA SNJ54AHC86J	Samples
SNJ54AHC86W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9681601QDA SNJ54AHC86W	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
										SNJ54AHC86W	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54AHC86, SN74AHC86 :

- Catalog : [SN74AHC86](#)

- Military : [SN54AHC86](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC86BQAR	WQFN	BQA	14	3000	180.0	12.4	2.8	3.3	1.1	4.0	12.0	Q1
SN74AHC86DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74AHC86DGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74AHC86DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHC86DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHC86NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AHC86PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHC86PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHC86RGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC86BQAR	WQFN	BQA	14	3000	210.0	185.0	35.0
SN74AHC86DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74AHC86DGVR	TVSOP	DGV	14	2000	356.0	356.0	35.0
SN74AHC86DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74AHC86DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74AHC86NSR	SO	NS	14	2000	356.0	356.0	35.0
SN74AHC86PWR	TSSOP	PW	14	2000	353.0	353.0	32.0
SN74AHC86PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74AHC86RGYR	VQFN	RGY	14	3000	356.0	356.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9681601Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9681601QDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74AHC86N	N	PDIP	14	25	506	13.97	11230	4.32
SN74AHC86N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54AHC86FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54AHC86W	W	CFP	14	25	506.98	26.16	6220	NA

D0014A



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

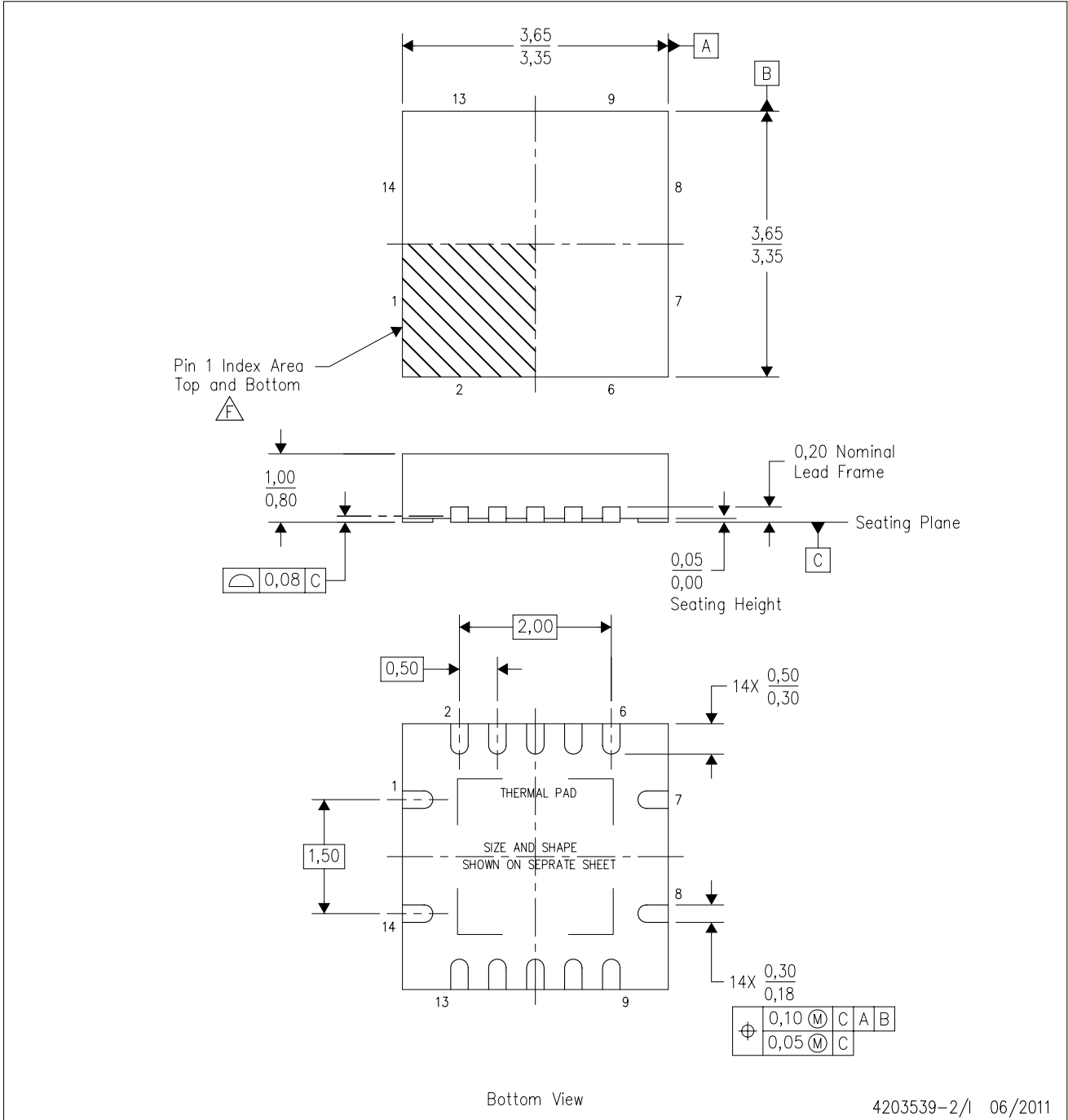
4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - F. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - G. Package complies to JEDEC MO-241 variation BA.

RGY (S-PVQFN-N14)

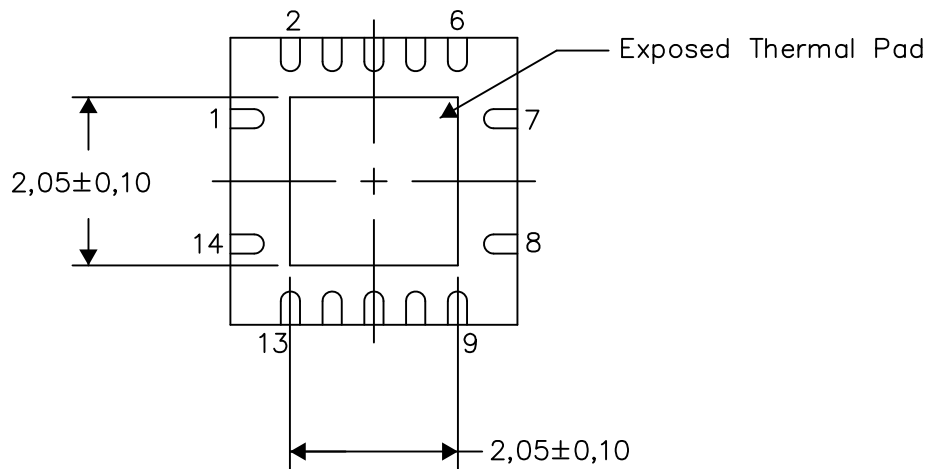
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

Exposed Thermal Pad Dimensions

4206353-2/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



4208122-2/P 03/14

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

GENERIC PACKAGE VIEW

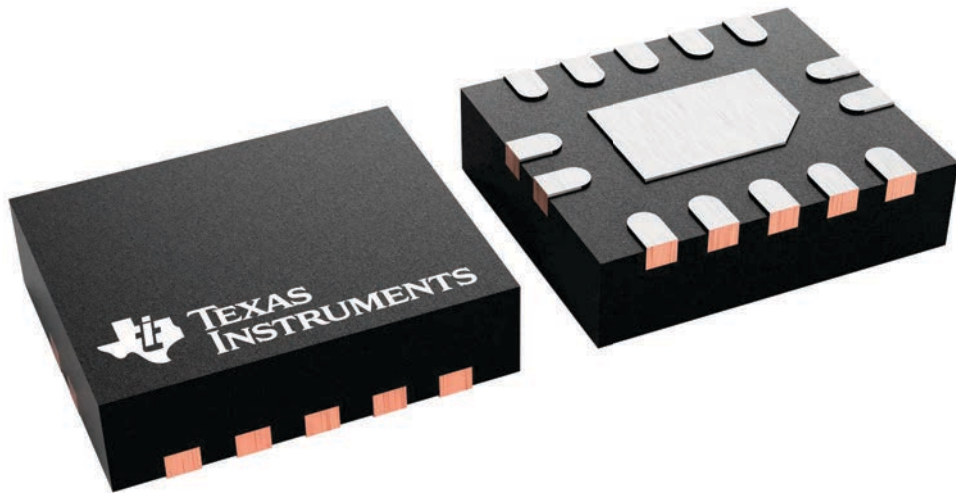
BQA 14

WQFN - 0.8 mm max height

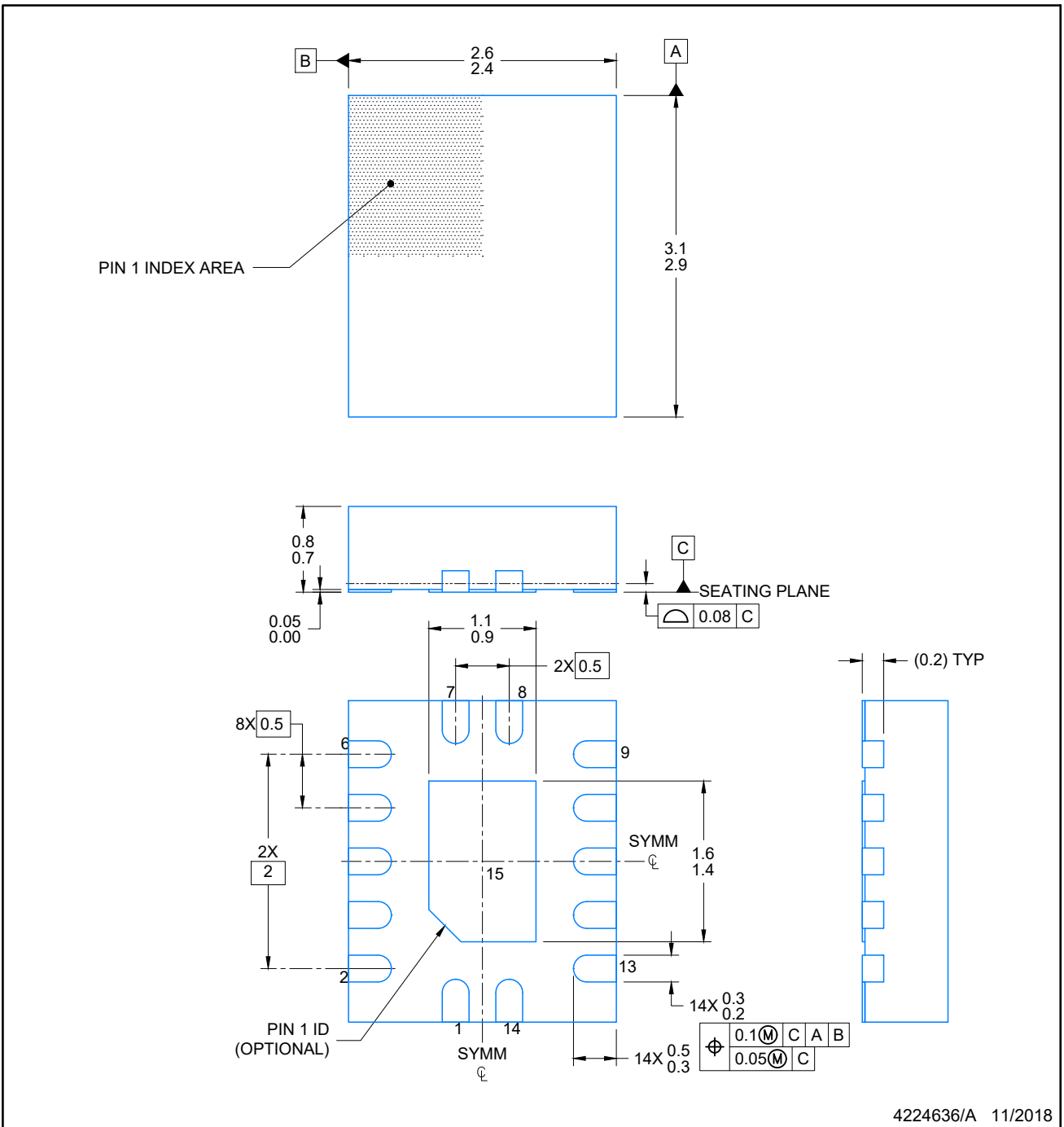
2.5 x 3, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4227145/A



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

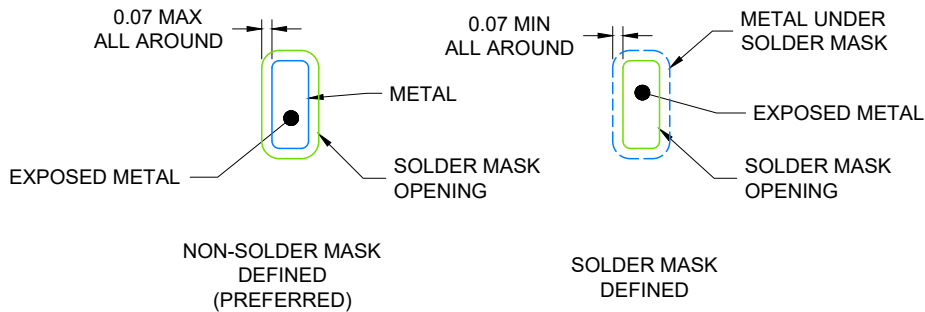
BQA0014A

WQFN - 0.8 mm max height

PLASTIC QUAD FLAT PACK-NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



4224636/A 11/2018

NOTES: (continued)

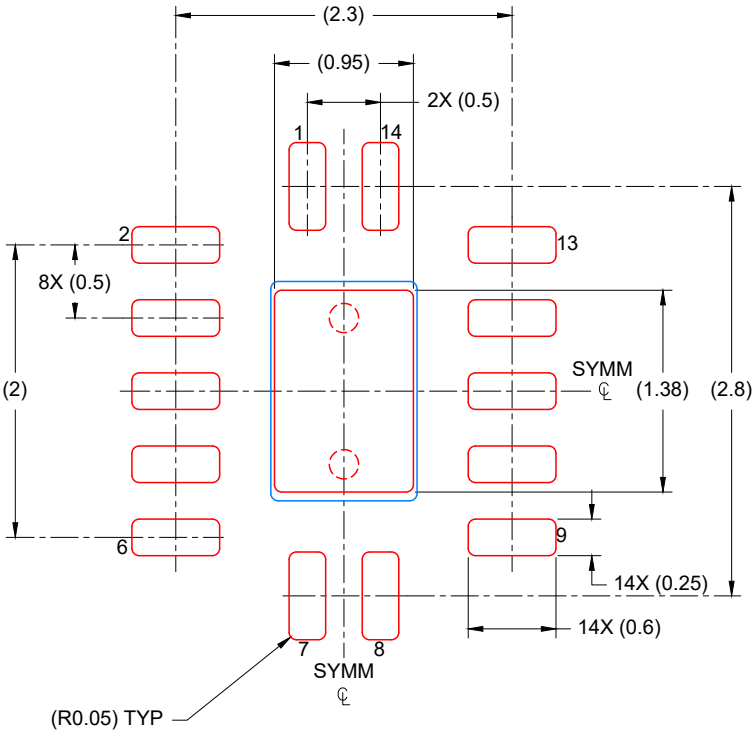
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

BQA0014A

WQFN - 0.8 mm max height

PLASTIC QUAD FLAT PACK-NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
88% PRINTED COVERAGE BY AREA
SCALE: 20X

4224636/A 11/2018

NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DB0014A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220762/A 05/2024

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

GENERIC PACKAGE VIEW

FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4229370VA\

J 14

GENERIC PACKAGE VIEW
CDIP - 5.08 mm max height
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



4214771/A 05/2017

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

PW0014A



PACKAGE OUTLINE
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220202/B 12/2023

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

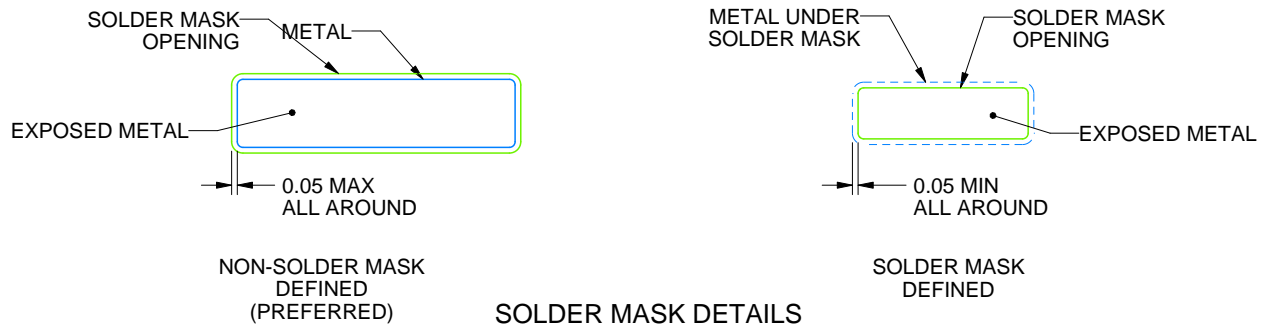
PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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